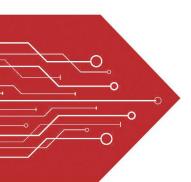
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data sheet













- 1. BASE
- 2. EMITTER
- 3. COLLECTOR

MARKING: 1N

TRANSISTOR (NPN)

MMBT3904T-MS **FEATURES**

- Complementary to MMBT3906T
- Small Package

MAXIMUM RATINGS (T_a=25°C unless otherwise noted)

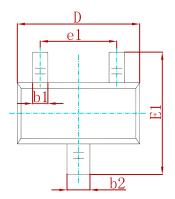
Symbol	Parameter	Value	Unit
V _{CBO}	Collector-Base Voltage	60	V
V _{CEO}	Collector-Emitter Voltage	40	V
V _{EBO}	Emitter-Base Voltage	6	V
Ic	Collector Current	200	mA
Pc	Collector Power Dissipation	150	mW
R _{⊙JA}	Thermal Resistance From Junction To Ambient	833	°C/W
T _J ,T _{stg}	Operation Junction and Storage Temperature Range	-55∼+150	℃

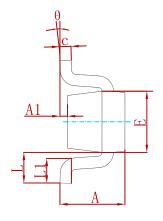
ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

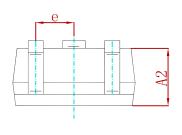
Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Collector-base breakdown voltage	V _{(BR)CBO}	I _C =10μA, I _E =0	60			V
Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C =1mA, I _B =0	40			V
Emitter-base breakdown voltage	V _{(BR)EBO}	I _E =10μA, I _C =0	6			V
Collector cut-off current	I _{CEX}	V _{CE} =30V, V _{EB(off)} =3V			50	nA
Emitter cut-off current	I _{EBO}	V _{EB} =5V, I _C =0			100	nA
	h _{FE(1)}	V _{CE} =1V, I _C =0.1mA	40			
DC assument resid	h _{FE(2)}	V _{CE} =1V, I _C =1mA	70			
DC current gain	h _{FE(3)}	V _{CE} =1V, I _C =10mA	100		300	
	h _{FE(4)}	V _{CE} =1V, I _C =50mA	60			
Collector emitter estimation values	V _{CE(sat)}	I _C =10mA, I _B =1mA			0.2	V
Collector-emitter saturation voltage		I _C =50mA, I _B =5mA			0.3	V
Collector emitter estimation values	V _{BE(sat)}	I _C =10mA, I _B =1mA	0.65		0.85	V
Collector-emitter saturation voltage		I _C =50mA, I _B =5mA			0.95	V
Transition frequency	f _T	V _{CE} =20V,I _C =10mA, f=100MHz	300			MHz
Collector output capacitance	C _{ob}	V _{CB} =5V, I _E =0, f=1MHz			4	pF
Base input capacitance	C _{ib}	V _{EB} =0.5V, I _C =0, f=1MHz			8	pF
Dalam the a	t _d	V _{CC} =3V, V _{BE(off)} =-0.5V I _C =10mA,		0.5	ns	
Delay time		I _{B1} =1mA		35		
Dies time	t _r	V _{CC} =3V, V _{BE(off)} =-0.5V I _C =10mA,			35	
Rise time		I _{B1} =1mA		35		ns
Storage time	ts	V _{CC} =3V, I _C =10mA, I _{B1} = I _{B2} =1mA			200	ns
Fall time	t _f	V _{CC} =3V, I _C =10mA, I _{B1} = I _{B2} =1mA			50	ns



PACKAGE MECHANICAL DATA

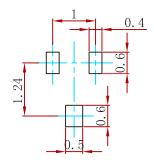






Comple ed	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	0.700	0.900	0.028	0.035	
A1	0.000	0.100	0.000	0.004	
A2	0.700	0.800	0.028	0.031	
b1	0.150	0.250	0.006	0.010	
b2	0.250	0.350	0.010	0.014	
С	0.100	0.200	0.004	0.008	
D	1.500	1.700	0.059	0.067	
E	0.700	0.900	0.028	0.035	
E1	1.450	1.750	0.057	0.069	
е	0.500	TYP.	0.020	TYP.	
e1	0.900	1.100	0.035	0.043	
L	0.400	REF.	0.016	REF.	
L1	0.260	0.460	0.010	0.018	
θ	0°	8°	0°	8°	

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MMBT3904T-MS	SOT-523	3000



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